

75Ω HIGH ISOLATION RF JACKS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?IJ7

Shell Material:

Copper Alloy

Insulator Material:

Black LCP

Contact Material:

Copper Alloy

Pin Material:

Copper Alloy

Dielectric Material:

Natural LCP

Plating:

Au or Sn over

50μ" (1.27 μm) Ni

Current Rating (Vertical):

Signal: 2.2 A per pin

(2 adjacent pins powered)

Grounds: 6.3 A per pin

(2 adjacent pins powered)

Operating Temp Range:

-55°C to +125°C

Insulation Resistance:

10,000 MΩ

Contact Resistance:

Signal: 26 mΩ

Grounds: 2.7 mΩ

Impedance:

75Ω

Dielectric Withstanding Voltage:

1950 VAC

Working Voltage:

650 VAC

RoHS Compliant:

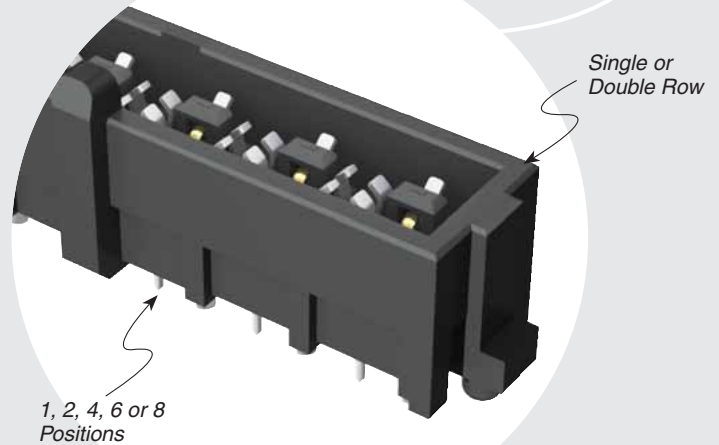
Yes

Processing:

Lead-Free Solderable:

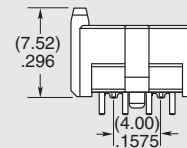
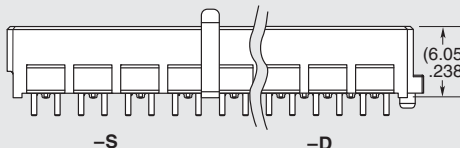
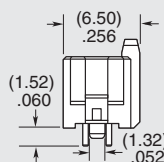
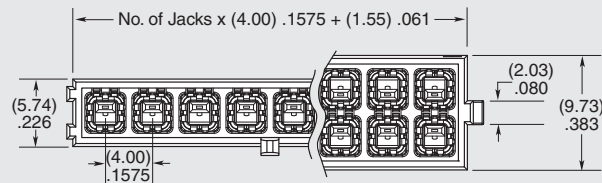
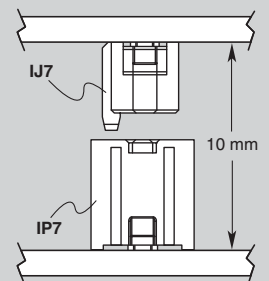
Yes

Mates with:
IP7



IJ7	JACKS PER ROW	05.0	PLATING	ROW OPTION	TAIL	TR
	-01, -02, -04, -06, -08		-L = 10μ" (0.25 μm) Gold on contact area, Matte Tin on tail	-S = Single Row -D = Double Row (Not available with -01)	-1 = (1.60 mm) .062" board thickness	-TR = Tape & Reel

APPLICATION



ALSO AVAILABLE (MOQ Required)

- Other stack heights
 - Other PCB thicknesses
- Contact Samtec.

OTHER SOLUTIONS

- 50Ω Board-to-Board system (see IJ5 & IP5 series)

Note: Designed to meet SMPTE 424M 3G SDI specifications.